

REV.	ECN NO	CONTENT	DATE	ENGINEER
A0				

NOTES:

1. MATERIAL

CONTACTS: COPPER ALLOY (T=0.20mm)
SHELL: SPCC OR COPPER ALLOY (T=0.30mm)
HOUSING: HIGH TEMPERATURE RESISTANT PLASTIC, UL94 V-0.

2. ELECTRICAL PERFORMANCE

CONTACT RESISTANCE: 30MΩ MAX
CONTACT CURRENT RATING: 1.5 AMPERES
DIELECTRIC WITHSTAND VOLTAGE, 500V R.M.S
INSULATION RESISTANCE: 100MΩ MIN
OPERATING TEMPERATURE: -40° C~+85° C.

3. MECHANICAL PERFORMANCE

INSERTION FORCE: 3.5kgf Max
REMOVAL FORCE: 1.02kgf Min
DURABILITY: 1000 CYCLES.

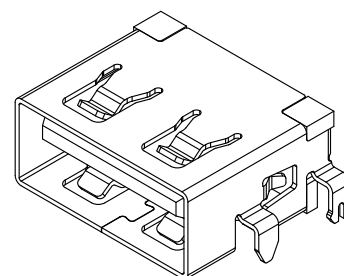
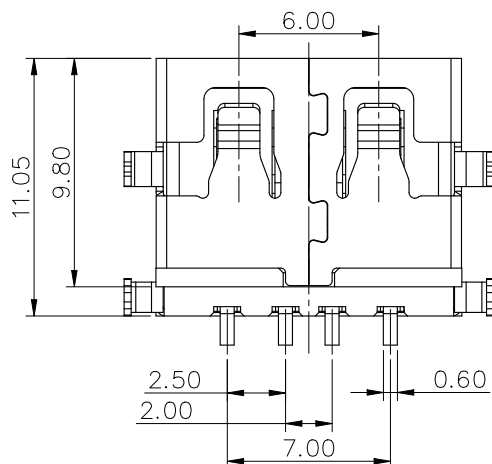
4. PLATING SPECIFICATION:

CONTACTS: GOLD PLATED ON CONTACT AREA, Sn ON SOLDER AREA,
NICKEL UNDERPLATED.
SHELL: BRIGHT NICKEL PLATING OVER ALL,
NICKEL MUST BE SOLDABILITY.
HOUSING: HIGH TEMPERATURE RESISTANT PLASTIC, UL94 V-0 .

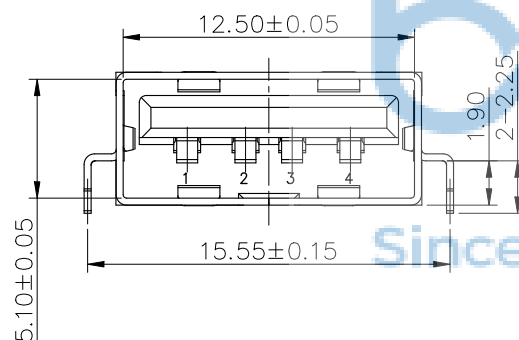
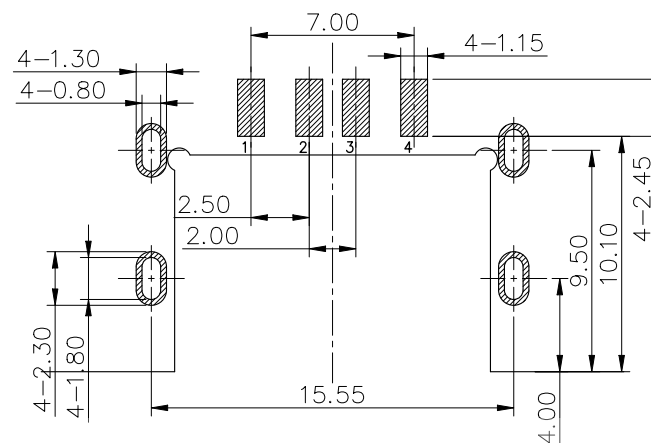


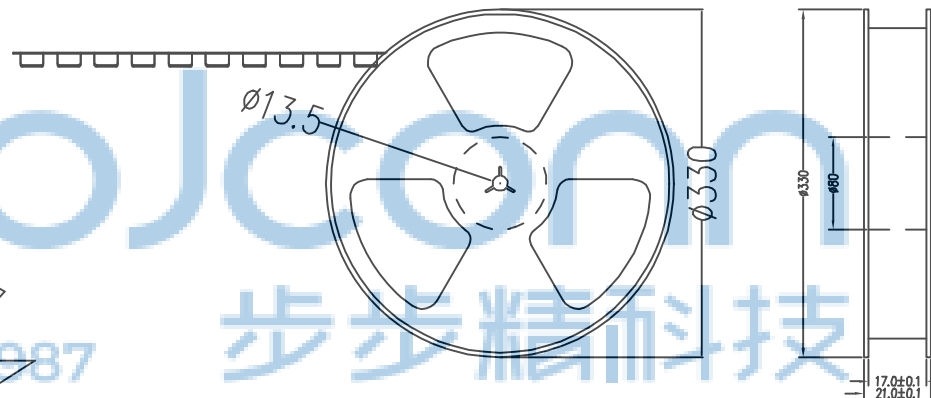
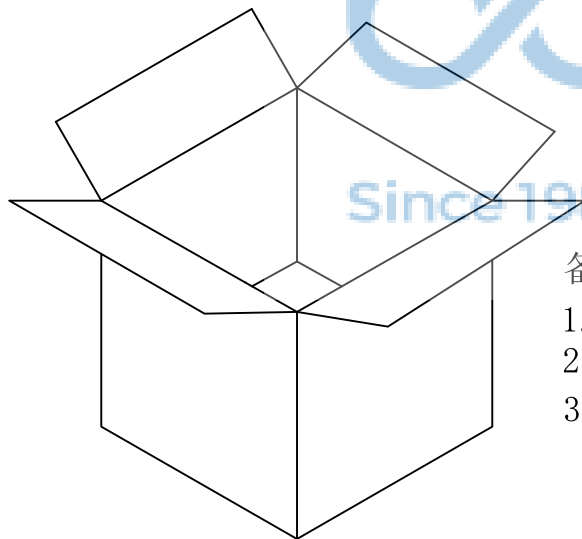
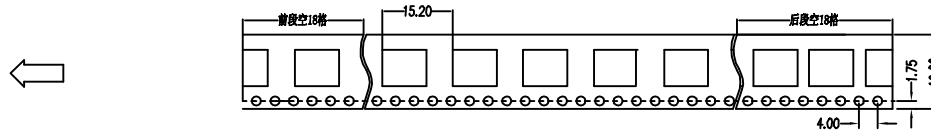
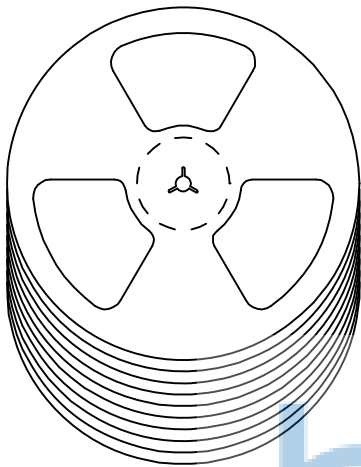
Pin Number	Signal Name
1	VBUS
2	D-
3	D+
4	GND

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.X: ±0.38	.XX: ±0.25	.XXX: ±0.13	X*: ±3°	.X*: ±2°	.XX*: ±1°
NAME: USB 2.0 AF 短体 L=11.05 沉板1.9 端子SMT 平口 LCP黑胶 铁壳 光面 (小米) (自编)		APPD. JM_Zheng		PJ. NO.: UB.01.32-11-1007	
CHKD. TSP		DR. LYX		SIZE: A4 DRW NO.:	
FINISH: SEE NOTES		SCALE: N/A		MAT'L.: SEE NOTES	
REV.: A0		UNIT: mm		PAGE: 1/2	



RECOMMENDED P.C.B HOLE LAYOUT
COMPONENT SIDE VIEW(TOLERANCE: +/-0.05)





备注:

1. 包装数量: 500/PCS/34i£-1034i/ïäj£
2. 包装袋长度: 每卷前后各空10-20个空格, 中间包装。
3. 材质:
 - 载体: 聚丙烯 (PS), 阻抗 $10^{6-9} \Omega$
 - 上带: 聚乙烯 (PET), 阻抗 $10^{6-11} \Omega$
 - 卷盘: 聚苯乙烯。

纸箱规格：345*345*23MM

纸箱规格：345*345*35MM

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PDWG,NO: 0100-2

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$\bar{X}: \pm 0.38$	$X^*: \pm 3$
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 $\cdot XX: \pm 0.25 \quad \cdot X^*: \pm 2$

.XXX: ± 0.13	.XX*: ± 1

APPD. JM_Zheng

	9
DATE	---

CHKD. TSP

DP	LV
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DR.	LIA
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NAME: USB 2.0 AF 11 05 3A 1 9 1E x OSMT

$$\{E_{1\frac{1}{2}} : \dot{\cup} \text{CB}^0\}_{1\frac{68}{100}} \dot{\cup} : C_{1\hat{A}\tilde{A}\infty} (\mathcal{D}:\tilde{A}\times) (\times\hat{O}+\hat{\lambda})$$
[illegible]

PJ. NO.: UB.01.32-11-1007

SIZE: A4 | DRW NO.:

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FINISH. SEE NOTES		MAT L.. SEE NOTES	
SCALE N/A	REV. 10	UNIT: mm	PAGE 2/2

SCALE: N/A REV.: A0 UNIT: mm PAGE: 2/2